



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	113
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200c-4tn144i

Features

■ Non-volatile, Infinitely Reconfigurable

- Instant-on – powers up in microseconds
- Single chip, no external configuration memory required
- Excellent design security, no bit stream to intercept
- Reconfigure SRAM based logic in milliseconds
- SRAM and non-volatile memory programmable through JTAG port
- Supports background programming of non-volatile memory

■ Sleep Mode

- Allows up to 100x static current reduction

■ TransFR™ Reconfiguration (TFR)

- In-field logic update while system operates

■ High I/O to Logic Density

- 256 to 2280 LUT4s
- 73 to 271 I/Os with extensive package options
- Density migration supported
- Lead free/RoHS compliant packaging

■ Embedded and Distributed Memory

- Up to 27.6 Kbits sysMEM™ Embedded Block RAM
- Up to 7.7 Kbits distributed RAM
- Dedicated FIFO control logic

■ Flexible I/O Buffer

- Programmable sysIO™ buffer supports wide range of interfaces:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2
 - LVTTTL
 - PCI
 - LVDS, Bus-LVDS, LVPECL, RSDS

■ sysCLOCK™ PLLs

- Up to two analog PLLs per device
- Clock multiply, divide, and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan
- Onboard oscillator
- Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
- IEEE 1532 compliant in-system programming

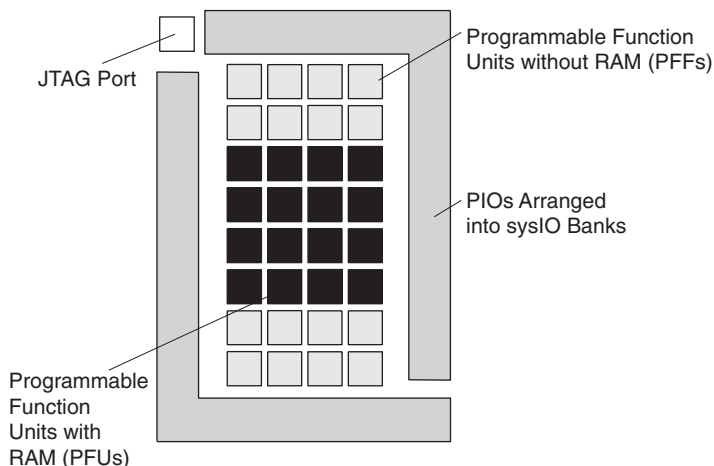
Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

Table 1-1. MachXO Family Selection Guide

Device	LCMX0256	LCMX0640	LCMX01200	LCMX02280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

Figure 2-3. Top View of the MachXO256 Device

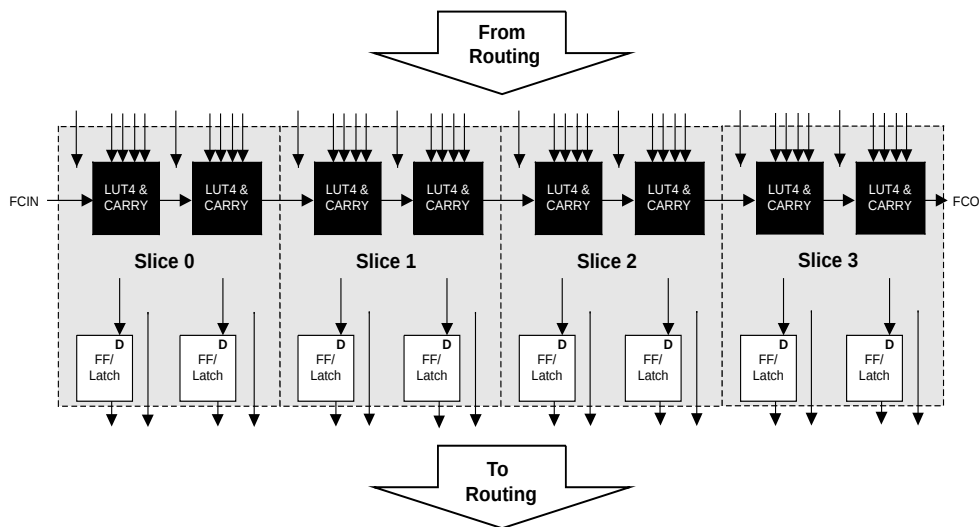


PFU Blocks

The core of the MachXO devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM, and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic, and Distributed ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected Slices, numbered 0-3 as shown in Figure 2-4. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-4. PFU Diagram



Slice

Each Slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7, and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select, and wider RAM/ROM functions. Figure 2-5 shows an overview of the internal logic of the Slice. The registers in the Slice can be configured for positive/negative and edge/level clocks.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
 - A greater-than-or-equal-to B
 - A not-equal-to B
 - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

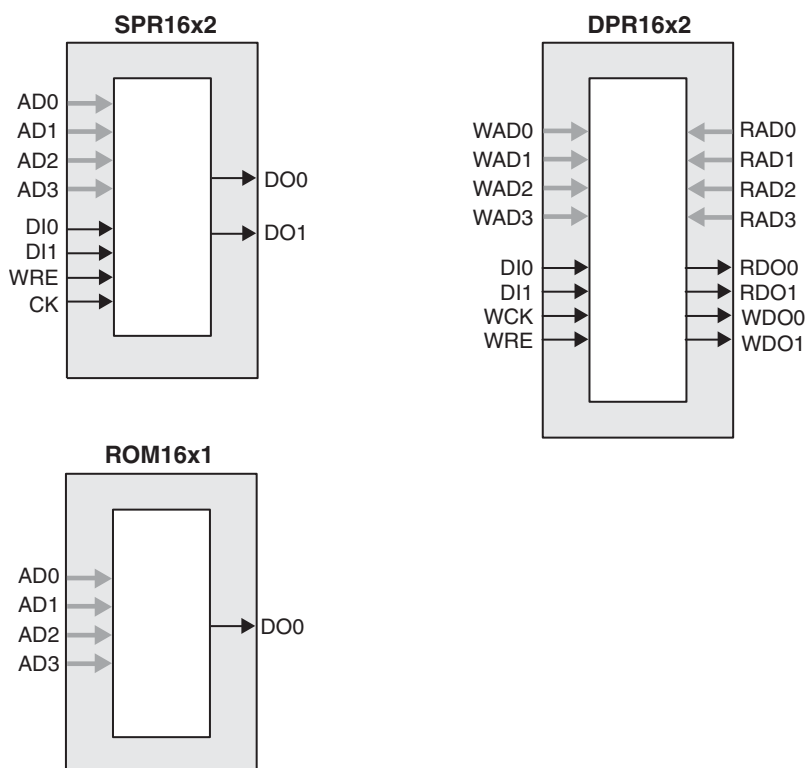
The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

Table 2-8. I/O Support Device by Device

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

Table 2-9. Supported Input Standards

Input Standard	VCCIO (Typ.)				
	3.3V	2.5V	1.8V	1.5V	1.2V
Single Ended Interfaces					
LVTTL	Yes	Yes	Yes	Yes	Yes
LVC MOS33	Yes	Yes	Yes	Yes	Yes
LVC MOS25	Yes	Yes	Yes	Yes	Yes
LVC MOS18			Yes		
LVC MOS15				Yes	
LVC MOS12	Yes	Yes	Yes	Yes	Yes
PCI ¹	Yes				
Differential Interfaces					
BLVDS ² , LVDS ² , LVPECL ² , RSDS ²	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.

2. MachXO1200 and MachXO2280 devices only.

Figure 2-18. MachXO2280 Banks

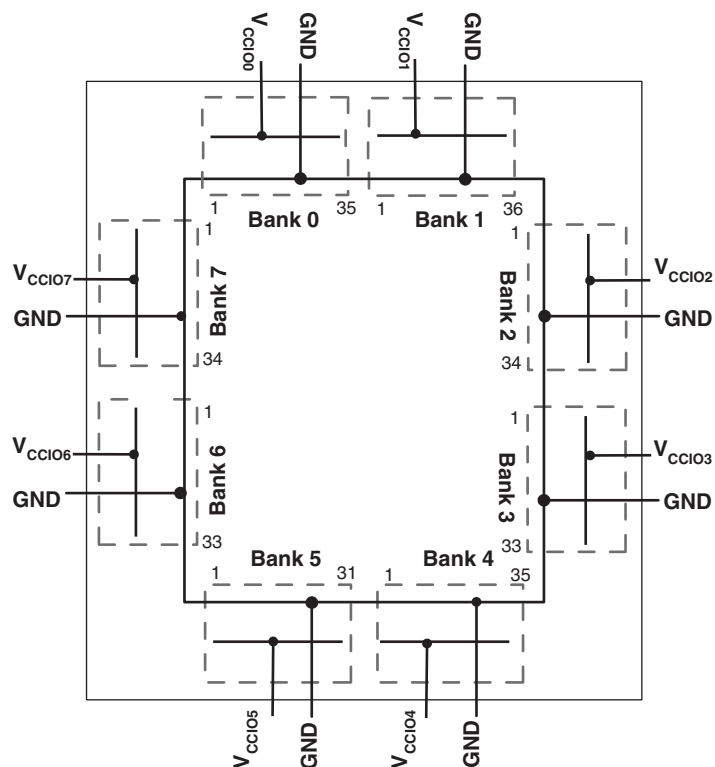
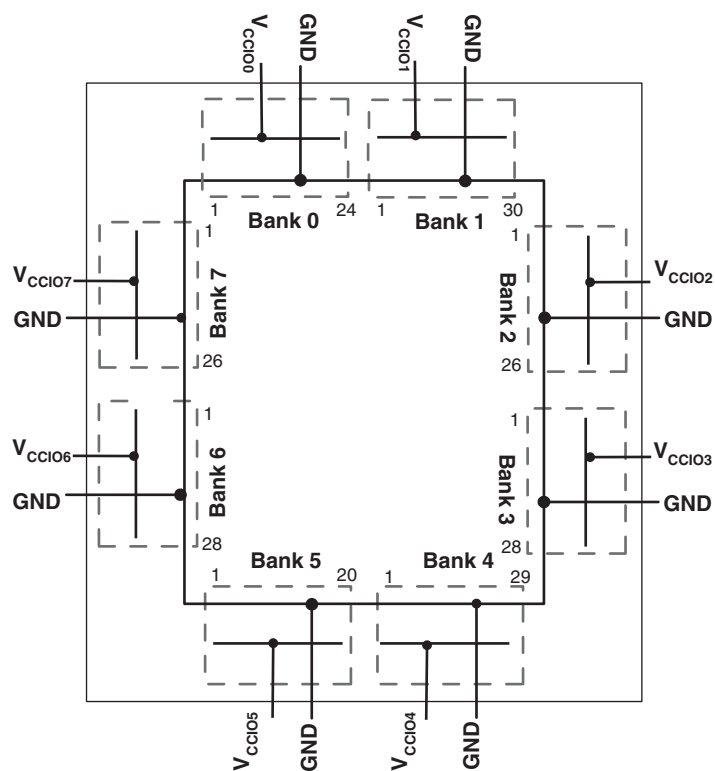


Figure 2-19. MachXO1200 Banks



For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

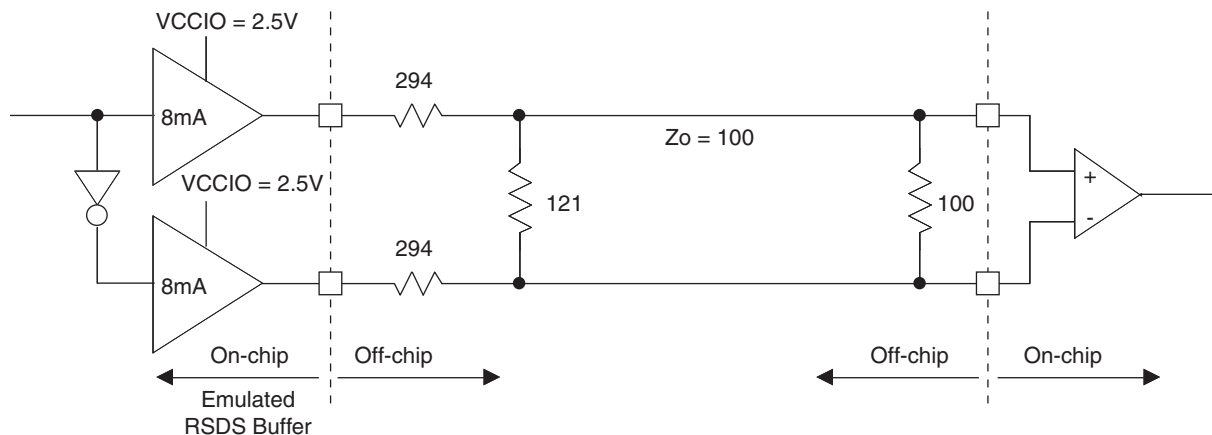


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

MachXO Internal Timing Parameters¹

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t _{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t _{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t _{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t _{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t _{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t _{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t _{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t _{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t _{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t _{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t _{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t _{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t _{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t _{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t _{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t _{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t _{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t _{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t _{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t _{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t _{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t _{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t _{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t _{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t _{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t _{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t _{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t _{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Rev. A 0.19

MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.

3. All other standards tested according to the appropriate specifications.

4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

Rev. A 0.19

Switching Test Conditions

Figure 3-6 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-6. Output Test Load, LVTTTL and LVCMOS Standards

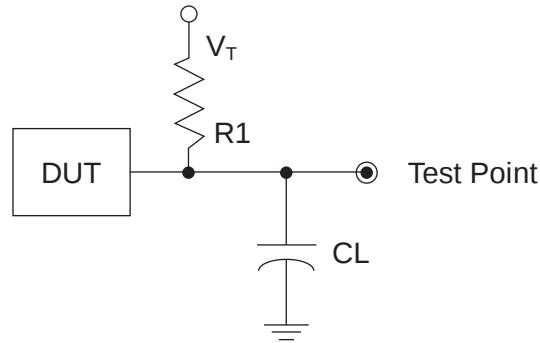


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R ₁	C _L	Timing Ref.	V _T
LVTTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTTL, LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = V _{CCIO} /2	—
			LVCMOS 1.8 = V _{CCIO} /2	—
			LVCMOS 1.5 = V _{CCIO} /2	—
			LVCMOS 1.2 = V _{CCIO} /2	—
LVTTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5	V _{OL}
LVTTTL and LVCMOS 3.3 (Z -> L)				V _{OH}
Other LVCMOS (Z -> H)			V _{CCIO} /2	V _{OL}
Other LVCMOS (Z -> L)			V _{CCIO} /2	V _{OH}
LVTTTL + LVCMOS (H -> Z)			V _{OH} - 0.15	V _{OL}
LVTTTL + LVCMOS (L -> Z)			V _{OL} - 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Power Supply and NC

Signal	100 TQFP ¹	144 TQFP ¹	100 csBGA ²
VCC	LCMXO256/640: 35, 90 LCMXO1200/2280: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	LCMXO256: 60, 74, 92 LCMXO640: 80, 92 LCMXO1200/2280: 94	LCMXO640: 117, 135 LCMXO1200/2280: 135	LCMXO256: H14, A14, B5 LCMXO640: B12, B5
VCCIO1	LCMXO256: 10, 24, 41 LCMXO640: 60, 74 LCMXO1200/2280: 80	LCMXO640: 82, 98 LCMXO1200/2280: 117	LCMXO256: G1, P1, P10 LCMXO640: H14, A14
VCCIO2	LCMXO256: None LCMXO640: 29, 41 LCMXO1200/2280: 70	LCMXO640: 38, 63 LCMXO1200/2280: 98	LCMXO256: None LCMXO640: P4, P10
VCCIO3	LCMXO256: None LCMXO640: 10, 24 LCMXO1200/2280: 56	LCMXO640: 10, 26 LCMXO1200/2280: 82	LCMXO256: None LCMXO640: G1, P1
VCCIO4	LCMXO256/640: None LCMXO1200/2280: 44	LCMXO640: None LCMXO1200/2280: 63	—
VCCIO5	LCMXO256/640: None LCMXO1200/2280: 27	LCMXO640: None LCMXO1200/2280: 38	—
VCCIO6	LCMXO256/640: None LCMXO1200/2280: 20	LCMXO640: None LCMXO1200/2280: 26	—
VCCIO7	LCMXO256/640: None LCMXO1200/2280: 6	LCMXO640: None LCMXO1200/2280: 10	—
VCCAUX	LCMXO256/640: 88 LCMXO1200/2280: 36, 90	53, 128	B7
GND ³	LCMXO256: 40, 84, 62, 75, 93, 12, 25, 42 LCMXO640: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 LCMXO1200/2280: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	LCMXO256: N9, B9, G14, B13, A4, H1, N2, N10 LCMXO640: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC ⁴			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
2. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
3. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
4. NC pins should not be connected to any active signals, VCC or GND.

LCMX0256 and LCMX0640 Logic Signal Connections: 100 csBGA

LCMX0256					LCMX0640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
B1	PL2A	1		T	B1	PL2A	3		T
C1	PL2B	1		C	C1	PL2C	3		T
D2	PL3A	1		T	D2	PL2B	3		C
D1	PL3B	1		C	D1	PL2D	3		C
C2	PL3C	1		T	C2	PL3A	3		T
E1	PL3D	1		C	E1	PL3B	3		C
E2	PL4A	1		T	E2	PL3C	3		T
F1	PL4B	1		C	F1	PL3D	3		C
F2	PL5A	1		T	F2	PL4A	3		
G2	PL5B	1		C	G2	PL4C	3		T
H1	GNDIO1	1			H1	GNDIO3	3		
H2	PL5C	1		T	H2	PL4D	3		C
J1	PL5D	1	GSRN	C	J1	PL5B	3	GSRN	
J2	PL6A	1		T	J2	PL7B	3		
K1	PL6B	1	TSALL	C	K1	PL8C	3	TSALL	T
K2	PL7A	1		T	K2	PL8D	3		C
L1	PL7B	1		C	L1	PL9A	3		
L2	PL7C	1		T	L2	PL9C	3		
M1	PL7D	1		C	M1	PL10A	3		
M2	PL8A	1		T	M2	PL10C	3		
N1	PL8B	1		C	N1	PL11A	3		
M3	PL9A	1		T	M3	PL11C	3		
N2	GNDIO1	1			N2	GNDIO3	3		
P2	TMS	1	TMS		P2	TMS	2	TMS	
P3	PL9B	1		C	P3	PB2C	2		
N4	TCK	1	TCK		N4	TCK	2	TCK	
P4	PB2A	1		T	P4	VCCIO2	2		
N3	PB2B	1		C	N3	GNDIO2	2		
P5	TDO	1	TDO		P5	TDO	2	TDO	
N5	PB2C	1		T	N5	PB4C	2		
P6	TDI	1	TDI		P6	TDI	2	TDI	
N6	PB2D	1		C	N6	PB4E	2		
P7	VCC	-			P7	VCC	-		
N7	PB3A	1	PCLK1_1**	T	N7	PB5B	2	PCLK2_1**	
P8	PB3B	1		C	P8	PB5D	2		
N8	PB3C	1	PCLK1_0**	T	N8	PB6B	2	PCLK2_0**	
P9	PB3D	1		C	P9	PB6C	2		
N10	GNDIO1	1			N10	GNDIO2	2		
P11	PB4A	1		T	P11	PB8B	2		
N11	PB4B	1		C	N11	PB8C	2		T
P12	PB4C	1		T	P12	PB8D	2		C
N12	PB4D	1		C	N12	PB9A	2		

LCMX0256 and LCMX0640 Logic Signal Connections: 100 csBGA (Cont.)

LCMX0256					LCMX0640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		T	B4	PT3B	0		C
A3	PT2F	0		C	A3	PT3A	0		T
B3	PT2E	0		T	B3	PT2F	0		C
A2	PT2D	0		C	A2	PT2E	0		T
C3	PT2C	0		T	C3	PT2B	0		C
A1	PT2B	0		C	A1	PT2C	0		
B2	PT2A	0		T	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

*NC for "E" devices.

**Primary clock inputs are single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	3		T	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2C	3		T	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL2B	3		C	PL3A	7		T*	PL3A	7		T*
4	PL3A	3		T	PL3B	7		C*	PL3B	7		C*
5	PL2D	3		C	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
6	PL3B	3		C	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
7	PL3C	3		T	PL4A	7		T*	PL4A	7		T*
8	PL3D	3		C	PL4B	7		C*	PL4B	7		C*
9	PL4A	3			PL4C	7			PL4C	7		
10	VCCIO3	3			VCCIO7	7			VCCIO7	7		
11	GNDIO3	3			GNDIO7	7			GNDIO7	7		
12	PL4D	3			PL5C	7			PL6C	7		
13	PL5A	3		T	PL6A	7		T*	PL7A	7		T*
14	PL5B	3	GSRN	C	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
15	PL5D	3			PL6D	7			PL7D	7		
16	GND	-			GND	-			GND	-		
17	PL6C	3		T	PL7C	7		T	PL9C	7		T
18	PL6D	3		C	PL7D	7		C	PL9D	7		C
19	PL7A	3		T	PL10A	6		T*	PL13A	6		T*
20	PL7B	3		C	PL10B	6		C*	PL13B	6		C*
21	VCC	-			VCC	-			VCC	-		
22	PL8A	3		T	PL11A	6		T*	PL13D	6		
23	PL8B	3		C	PL11B	6		C*	PL14D	6		C
24	PL8C	3	TSALL		PL11C	6	TSALL		PL14C	6	TSALL	T
25	PL9C	3		T	PL12B	6			PL15B	6		
26	VCCIO3	3			VCCIO6	6			VCCIO6	6		
27	GNDIO3	3			GNDIO6	6			GNDIO6	6		
28	PL9D	3		C	PL13D	6			PL16D	6		
29	PL10A	3		T	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
30	PL10B	3		C	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
31	PL10C	3		T	PL14C	6		T	PL17C	6		T
32	PL11A	3		T	PL14D	6		C	PL17D	6		C
33	PL10D	3		C	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
34	PL11C	3		T	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
35	PL11B	3		C	PL16A	6		T	PL19A	6		T
36	PL11D	3		C	PL16B	6		C	PL19B	6		C
37	GNDIO2	2			GNDIO5	5			GNDIO5	5		
38	VCCIO2	2			VCCIO5	5			VCCIO5	5		
39	TMS	2	TMS		TMS	5	TMS		TMS	5	TMS	
40	PB2C	2			PB2C	5		T	PB2A	5		T
41	PB3A	2		T	PB2D	5		C	PB2B	5		C
42	TCK	2	TCK		TCK	5	TCK		TCK	5	TCK	
43	PB3B	2		C	PB3A	5		T	PB3A	5		T
44	PB3C	2		T	PB3B	5		C	PB3B	5		C
45	PB3D	2		C	PB4A	5		T	PB4A	5		T
46	PB4A	2		T	PB4B	5		C	PB4B	5		C
47	TDO	2	TDO		TDO	5	TDO		TDO	5	TDO	
48	PB4B	2		C	PB4D	5			PB4D	5		
49	PB4C	2		T	PB5A	5		T	PB5A	5		T
50	PB4D	2		C	PB5B	5		C	PB5B	5		C

LCMXO2280 Logic Signal Connections: 324 ftBGA

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO7	7		
VCCIO7	VCCIO7	7		
D4	PL2A	7	LUM0_PLLT_FB_A	T
F5	PL2B	7	LUM0_PLLC_FB_A	C
B3	PL3A	7		T*
C3	PL3B	7		C*
E4	PL3C	7	LUM0_PLLT_IN_A	T
G6	PL3D	7	LUM0_PLLC_IN_A	C
A1	PL4A	7		T*
B1	PL4B	7		C*
F4	PL4C	7		T
VCC	VCC	-		
E3	PL4D	7		C
D2	PL5A	7		T*
D3	PL5B	7		C*
G5	PL5C	7		T
F3	PL5D	7		C
C2	PL6A	7		T*
VCCIO7	VCCIO7	7		
GND	GNDIO7	7		
C1	PL6B	7		C*
H5	PL6C	7		T
G4	PL6D	7		C
E2	PL7A	7		T*
D1	PL7B	7	GSRN	C*
J6	PL7C	7		T
H4	PL7D	7		C
F2	PL8A	7		T*
E1	PL8B	7		C*
GND	GND	-		
J3	PL8C	7		T
J5	PL8D	7		C
G3	PL9A	7		T*
H3	PL9B	7		C*
K3	PL9C	7		T
K5	PL9D	7		C
F1	PL10A	7		T*
VCCIO7	VCCIO7	7		
GND	GNDIO7	7		
G1	PL10B	7		C*
K4	PL10C	7		T
K6	PL10D	7		C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR10C	2		T
M18	PR10B	2		C*
L18	PR10A	2		T*
GND	GNDIO2	2		
VCCIO2	VCCIO2	2		
H16	PR9D	2		C
H14	PR9C	2		T
K18	PR9B	2		C*
J18	PR9A	2		T*
J17	PR8D	2		C
VCC	VCC	-		
H18	PR8C	2		T
H17	PR8B	2		C*
G17	PR8A	2		T*
H13	PR7D	2		C
H15	PR7C	2		T
G18	PR7B	2		C*
F18	PR7A	2		T*
G14	PR6D	2		C
G16	PR6C	2		T
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
E18	PR6B	2		C*
F17	PR6A	2		T*
G13	PR5D	2		C
G15	PR5C	2		T
E17	PR5B	2		C*
E16	PR5A	2		T*
GND	GND	-		
F15	PR4D	2		C
E15	PR4C	2		T
D17	PR4B	2		C*
D18	PR4A	2		T*
B18	PR3D	2		C
C18	PR3C	2		T
C16	PR3B	2		C*
D16	PR3A	2		T*
C17	PR2B	2		C
D15	PR2A	2		T
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
GND	GNDIO1	1		
VCCIO1	VCCIO1	1		

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
E13	PT16D	1		C
C15	PT16C	1		T
F13	PT16B	1		C
D14	PT16A	1		T
A18	PT15D	1		C
B17	PT15C	1		T
A16	PT15B	1		C
A17	PT15A	1		T
VCC	VCC	-		
D13	PT14D	1		C
F12	PT14C	1		T
C14	PT14B	1		C
E12	PT14A	1		T
C13	PT13D	1		C
B16	PT13C	1		T
B15	PT13B	1		C
A15	PT13A	1		T
VCCIO1	VCCIO1	1		
GND	GNDIO1	1		
B14	PT12F	1		C
A14	PT12E	1		T
D12	PT12D	1		C
F11	PT12C	1		T
B13	PT12B	1		C
A13	PT12A	1		T
C12	PT11D	1		C
GND	GND	-		
B12	PT11C	1		T
E11	PT11B	1		C
D11	PT11A	1		T
C11	PT10F	1		C
A12	PT10E	1		T
VCCIO1	VCCIO1	1		
GND	GNDIO1	1		
F10	PT10D	1		C
D10	PT10C	1		T
B11	PT10B	1	PCLK1_1***	C
A11	PT10A	1		T
E10	PT9D	1		C
C10	PT9C	1		T
D9	PT9B	1	PCLK1_0***	C
E9	PT9A	1		T
B10	PT8F	0		C

For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, [MachXO sysIO Usage Guide](#)
- TN1089, [MachXO sysCLOCK Design and Usage Guide](#)
- TN1092, [Memory Usage Guide for MachXO Devices](#)
- TN1090, [Power Estimation and Management for MachXO Devices](#)
- TN1086, [MachXO JTAG Programming and Configuration User's Guide](#)
- TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#)
- TN1097, [MachXO Density Migration](#)
- AN8066, [Boundary Scan Testability with Lattice sysIO Capability](#)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTTL, LVCMOS): www.jedec.org
- PCI: www.pcisig.com

Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	"Top View of the MachXO1200 Device" figure updated.
			"Top View of the MachXO640 Device" figure updated.
			"Top View of the MachXO256 Device" figure updated.
			"Slice Diagram" figure updated.
			Slice Signal Descriptions table updated.
			Routing section updated.
			sysCLOCK Phase Locked Loops (PLLs) section updated.
			PLL Diagram updated.
			PLL Signal Descriptions table updated.
			sysMEM Memory section has been updated.
			PIO Groups section has been updated.
			PIO section has been updated.
			MachXO PIO Block Diagram updated.
			Supported Input Standards table updated.
			MachXO Configuration and Programming diagram updated.
		DC and Switching Characteristics	Recommended Operating Conditions table - footnotes updated.
			MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.
			Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.
			DC Electrical Characteristics, footnotes have been updated.
			Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.
			Supply Current (Standby) table and associated footnotes updated.
			Initialization Supply Current table and footnotes updated.
			Programming and Erase Flash Supply Current table and associated footnotes have been updated.
			Register-to-Register Performance table updated (rev. A 0.19).
			MachXO External Switching Characteristics updated (rev. A 0.19).
			MachXO Internal Timing Parameters updated (rev. A 0.19).
			MachXO Family Timing Adders updated (rev. A 0.19).
			sysCLOCK Timing updated (rev. A 0.19).
			MachXO "C" Sleep Mode Timing updated (A 0.19).
			JTAG Port Timing Specification updated (rev. A 0.19).
			Test Fixture Required Components table updated.
		Pinout Information	Signal Descriptions have been updated.
			Pin Information Summary has been updated. Footnote has been added.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connections have been updated (PCLKTx_x --> PCLKx_x)
		Ordering Information	Removed "4W" references.
			Added 256-ftBGA Ordering Part Numbers for MachXO640.
May 2006	02.1	Pinout Information	Removed [LOC][0]_PLL_RST from Signal Description table.
			PCLK footnote has been added to all appropriate pins.
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.